


I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted via the Office electronic filing system in accordance with § 1.6(a)(4).

Dated: 8-9-2007 Signature: 
Nan Z. Carr

Docket No.: APPM/007385/PPC/ECP/CKIM
1016.012390
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	§	
Deenesh Padhi, et al.	§	
	§	Group Art Unit: 1753
Serial No.: 10/678,003	§	
	§	
Confirmation No.: 9225	§	Examiner: Edna Wong
	§	
Filed: October 2, 2003	§	
	§	
For: HOMOGENEOUS	§	
COPPER-PALLADIUM ALLOY	§	
PLATING FOR ENHANCEMENT OF	§	
ELECTRO-MIGRATION	§	
RESISTANCE IN INTERCONNECTS	§	

AMENDMENT IN RESPONSE TO RESTRICTION REQUIREMENT

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Restriction Requirement dated July 9, 2007, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.